

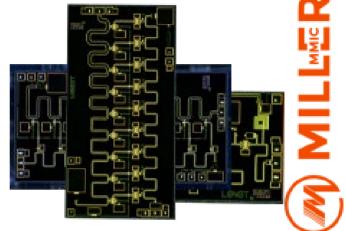
GaAs MMIC Two Channel Series
Fixed Attenuator DC-40GHz

Features

- · Ultra broadband two channel attenuator
- Frequency Range: DC 40GHz
- 2 Channels with 2 different Attenuation value
- Power Handling: 27dBm
- 50Ω Input and Output Impedance
- Return Loss: 20dB
- Bare Die (QFN Available)
- RoHS & REACH Compliant



- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- General Purpose



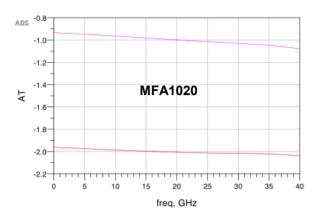
Part No.	Product Description	Frequency (GHz)	Channel	Attenuation (dB)	Power (dBm)	Flatness (dB)	VSWR
MFA1020	2 Channel Fixed Attenuator	DC-40	2	1dB / 2dB	27	±0.3	1.22
MFA1021	2 Channel Fixed Attenuator	DC-40	2	3dB / 4dB	27	±0.3	1.22
MFA1022	2 Channel Fixed Attenuator	DC-40	2	3dB / 5dB	27	±0.3	1.22
MFA1023	2 Channel Fixed Attenuator	DC-40	2	5dB / 7dB	27	±0.3	1.22
MFA1024	2 Channel Fixed Attenuator	DC-40	2	5dB / 8dB	27	±0.3	1.22
MFA1025	2 Channel Fixed Attenuator	DC-40	2	7dB / 8dB	27	±0.3	1.22
MFA1026	2 Channel Fixed Attenuator	DC-40	2	9dB / 10dB	27	±0.35	1.22
MFA1027	2 Channel Fixed Attenuator	DC-40	2	15dB / 20dB	27	±0.4	1.22

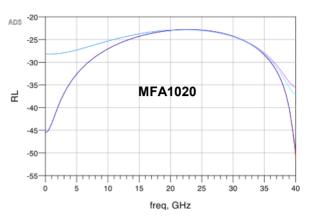
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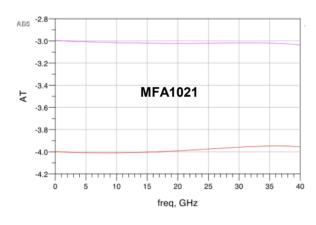
Sales: sales@millermmic.com Technical: support@millermmic.com

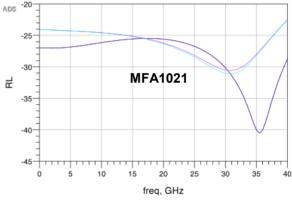


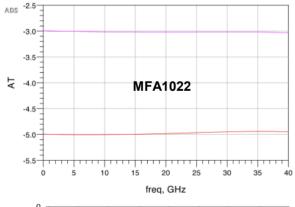
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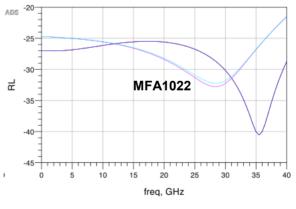


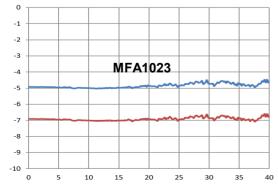


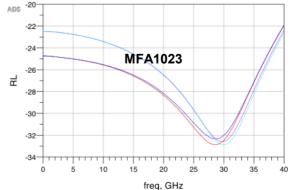






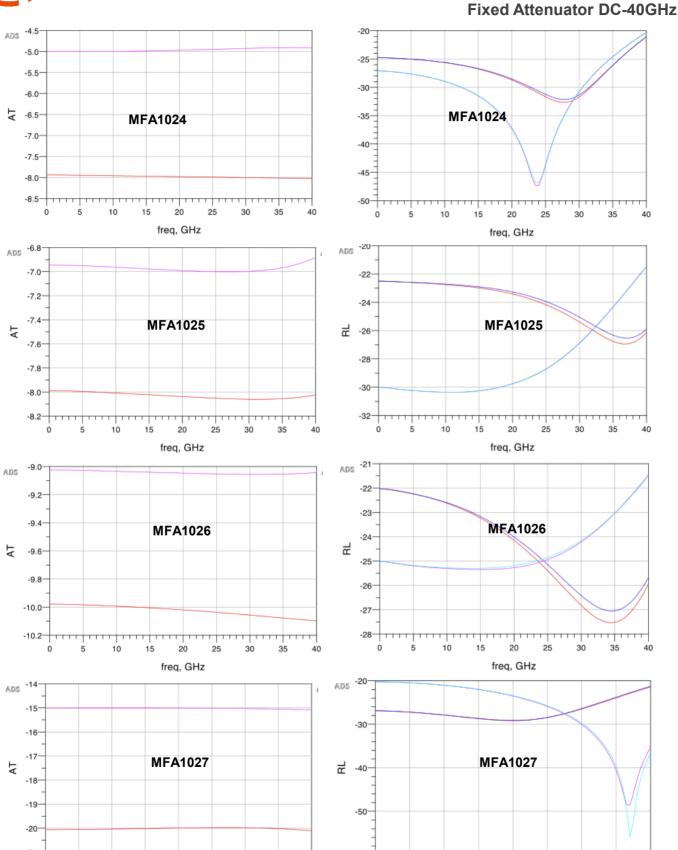








GaAs MMIC Two Channel Series



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Sales: sales@millermmic.com Technical: support@millermmic.com

30

freq, GHz

10

15

20

freq, GHz

25

30

35

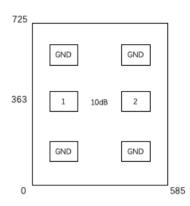


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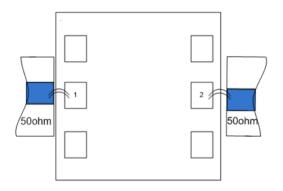
Outline Drawing:

All Dimensions in µm

Pad	Function	Description		
1	RF IN	RF signal input terminal; DC blocking capacitor required.		
2	RF OUT	RF signal output terminal; DC blocking capacitor required.		
Die bottom GND		Die bottom must be connected to RF/DC ground.		



Assembly Drawing



Notes:

1. Die thickness: 100 µm

2. Typical bond pad is 100*100 µm²
3. Bond pad metalization: Gold
4. Backside metalization: Gold

5. Backside of the die (GND)

6. No connection required for unlabeled bond pads

Maximum Ratings:

1. Maximum input power: +27dBm

2. Operating temperature: -55°C to +85°C

3. Storage temperature: -65°C to +150°C

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